

The PostProcess™ DEMI 800™ Series leverages our proprietary patented Submersed Vortex Cavitation technology for revolutionary post-printing efficiencies; combining software, hardware, and chemistry features for optimal resin and support removal.

- AUTOMAT3D® intelligent software control of energy sources and simplified machine operation.
- Vortex pumping scheme ensures uniform chemistry exposure to finishes parts with unprecedented consistency.
- Precision control over temperature and ultrasonic-generated cavitations for accelerated process times.
- Variable energy output to adapt to material and geometry needs results in reduced damage.



SOFTWARE FEATURES

- Variable temperature: 86-145°F / 30 – 63°C
- Programmable cycle time
- Proprietary *Agitation Algorithms*
- Recipe storage and recall
- Preventative maintenance features

HARDWARE FEATURES

- Stainless steel envelope
- Hinged envelope lid
- Process drain rack
- Magnetically driven pump
- Multi-configuration fixture
- Casters for easy installation

ELECTRICAL - NORTH AMERICA DEMI 800 MODEL

- 120V, 20A, Connector: NEMA L5-20P

DEMI 830-120V MODEL

- 120V, 20A, Connector: NEMA L5-20P
- Dual agitation; includes heater & 1,000 W ultrasonics

DEMI 830-240V MODEL

- 240V, 20A, Connector: ABB332P6W
- Dual agitation; includes heater & 1,750 W ultrasonic

ELECTRICAL - EUROPE

DEMI 830-230V MODEL

- 230V, 20A, Connector: ABB332P6W
- Dual agitation; includes heater & 1,750 W ultrasonics

MATERIALS AND TECHNOLOGIES



SLA



DLP



CLIP



FDM



POLYJET

Resin Removal

Support Removal

SIZE

Envelope: 18" L x 18" W x 18" H
46 cm x 46 cm x 46 cm

Footprint: 34.75" L x 43.5" W x 59.75" H
88 cm x 110 cm x 152 cm

Weight: 700 lbs / 318 kg empty, 1000 lbs / 454 kg full

CONSUMABLES

Capacity: 40 Gallons / 151 Liters

Detergent: PLM-101-SUB for Polyjet
PLM-201-SUB for FDM
PLM-403-SUB for SLA, CLIP, DLP

SAFETY FEATURES

- Emergency stop
- Auto power down
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